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Abstract of Japanese Patent Office Gazette

No. S60-195957

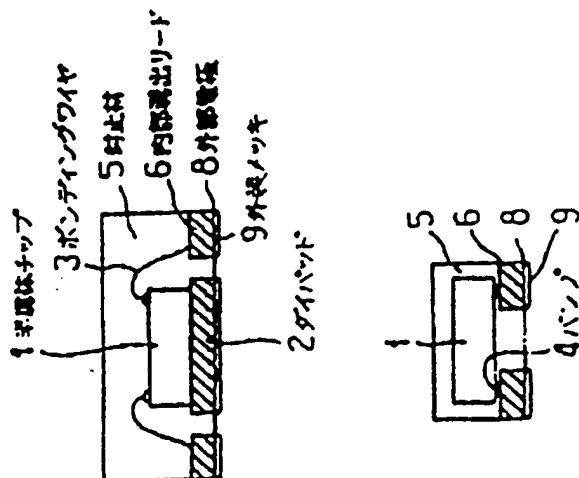
LEAD FRAME

Inventor: Tanigawa Takahiro, et al.
Applicant: Hitachi Ltd.
Filed: Mar. 19, 1984
Disclosed: Oct. 4, 1985

PURPOSE: To improve the contacting property between a lead frame and a resin and to enhance the sealability and the reliability by stepwisely forming the side of the lead frame, and increasing the contacting surface with the resin.

CONSTITUTION: Projections 8, 15 are formed on tabs 4, 13 of a lead frame, tab hanging lead 5 and the sides of leads 6, 14. The projection 8 is formed by a suitable method. The lead frame 12 is, for example, composed of 42-alloy. A semiconductor chip 9 is formed, for example, of silicon single crystal substrate, many circuit elements are formed in the chip by the know technique, and one circuit function is formed. A resin sealer 11 is formed, for example, of epoxy resin, and molded by a known transfer molding method.

★SONY U11 93-202142/25 ★JP05129473-A
 Mould package flat-face mounting type semiconductor device -
 exposes bottom surfaces of die pad and inner leads of bottom surface
 of mould package semiconductor device to be directly connected to
 circuit pattern of PCB NoAbstract
 SONY CORP 91.11.06 91JP-289882
 (93.05.25) H01L 23/28, 23/12, 23/28, 23/50
 (6pp Dwg.No.1/13) U11-D01A3 U11-D03A9
 N98-155203



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